

# CMS25N03V8-HF

**N-Channel**  
**RoHS Device**  
**Halogen Free**

## Features

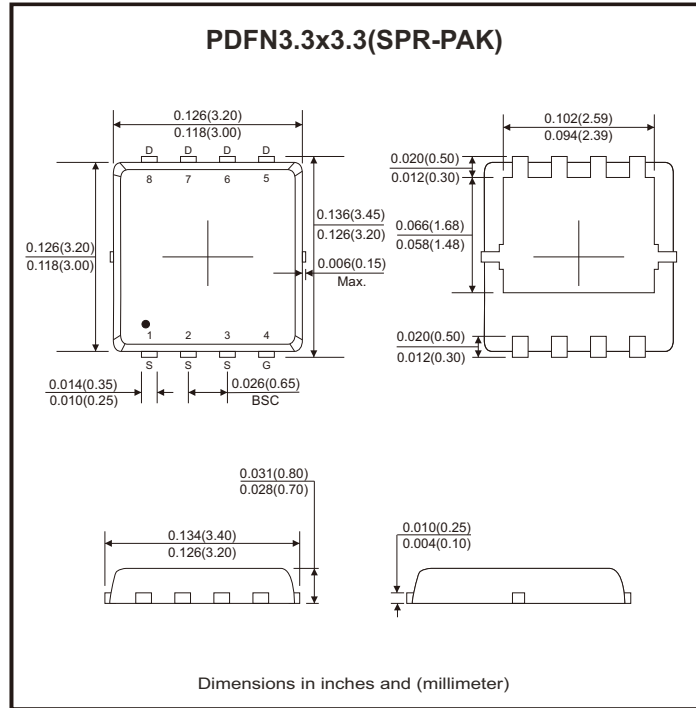
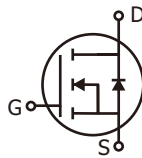
- Advanced high cell density trench technology.
- Super low gate charge.
- Excellent  $cdv/dt$  effect decline.
- Green device available.
- 100% EAS guaranteed.

## Mechanical data

- Case: PDFN3.3x3.3/SPR-PAK standard package, molded plastic.

## Circuit diagram

- G : Gate
- S : Source
- D : Drain



## Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
Drain-source voltage		$V_{DS}$	30	V
Gate-source voltage		$V_{GS}$	$\pm 20$	V
Continuous drain current (Note 1)	$I_D @ T_C = 25^\circ C$		25	A
	$I_D @ T_C = 100^\circ C$		16	
Pulsed drain current (Note 1, 2)		$I_{DM}$	55	A
Total power dissipation (Note 4)	$P_D @ T_C = 25^\circ C$		20	W
	$P_D @ T_A = 25^\circ C$		1.7	
Single pulse avalanche energy, $L=0.1mH$ (Note 3)		$E_{AS}$	22	mJ
Single pulse avalanche current, $L=0.1mH$ (Note 3)		$I_{AS}$	21	A
Operating junction temperature range		$T_J$	-55 to +150	$^\circ C$
Storage temperature range		$T_{STG}$	-55 to +150	$^\circ C$
Thermal resistance junction-ambient (Note 1)	Steady state	$R_{\theta JA}$	75	$^\circ C/W$
Thermal resistance junction-case (Note 1)	Steady state	$R_{\theta JC}$	6	$^\circ C/W$

**Electrical Characteristics** (at  $T_J=25^{\circ}\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.8	2.5	
Gate-source leakage current	$I_{GSS}$	$V_{GS} = \pm 20V$			$\pm 100$	nA
Drain-source leakage current ( $T_J=25^{\circ}\text{C}$ )	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V$			1	$\mu A$
Drain-source leakage current ( $T_J=55^{\circ}\text{C}$ )		$V_{DS} = 24V, V_{GS} = 0V$			5	
Static drain-source on-resistance (Note 2)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 10A$		15	18	m $\Omega$
		$V_{GS} = 4.5V, I_D = 5A$		21	28	
Total gate charge (Note 2)	$Q_g$	$I_D = 10A, V_{DS} = 20V, V_{GS} = 4.5V$		7.2		nC
Gate-source charge	$Q_{gs}$			1.4		
Gate-drain ("miller") charge	$Q_{gd}$			2.2		
Turn-on delay time (Note 2)	$t_{d(on)}$	$V_{DS} = 12V, V_{GS} = 10V$ $I_D = 5A, R_G = 3.3\Omega$		4.1		nS
Rise time	$t_r$			9.8		
Turn-off delay time	$t_{d(off)}$			15.5		
Fall time	$t_f$			6.0		
Input capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		572		$\mu F$
Output capacitance	$C_{oss}$			81		
Reverse transfer capacitance	$C_{rss}$			65		
Gate resistance	$R_g$	$f = 1MHz$		2.5		$\Omega$
<b>Source-drain diode</b>						
Diode forward voltage (Note 2)	$V_{SD}$	$I_S = 10A, V_{GS} = 0V, T_J=25^{\circ}\text{C}$			1.2	V
Continuous source current (Note 1,6)	$I_S$	$V_G = V_D = 0V, \text{Force current}$			25	A
Pulsed source current (Note 2,6)	$I_{SM}$				50	A
<b>Guaranteed avalanche characteristics</b>						
Single pulse avalanche energy (Note 5)	EAS	$V_{DD} = 25V, L=0.1mH, I_{AS} = 10A$	5			mJ

- Notes: 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2 oz copper.  
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .  
3. The EAS data shows max. rating. The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=21A$ .  
4. The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature.  
5. The min. value is 100% EAS tested guarantee.  
6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

## Rating and Characteristic Curves (CMS25N03V8-HF)

Fig.1 - Typical Output Characteristics

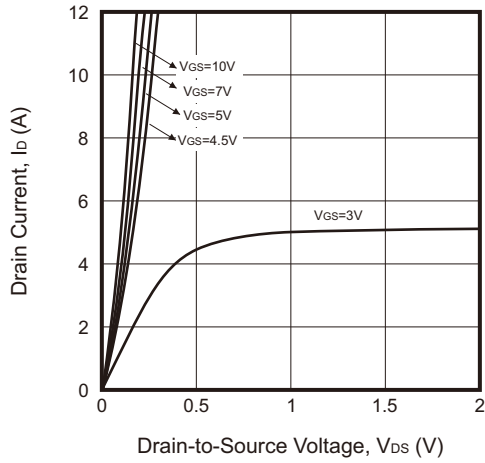


Fig.2 - On-Resistance vs. G-S Voltage

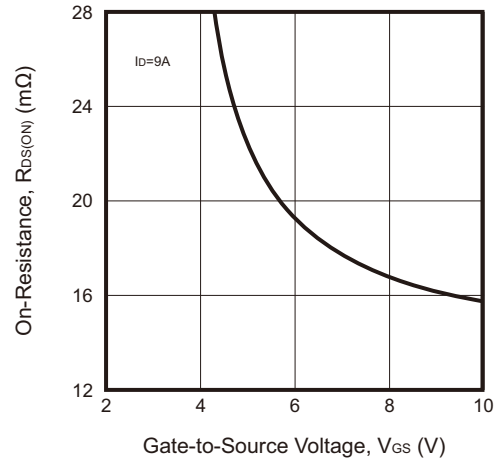


Fig.3 - Normalized  $V_{GS(th)}$  vs.  $T_J$

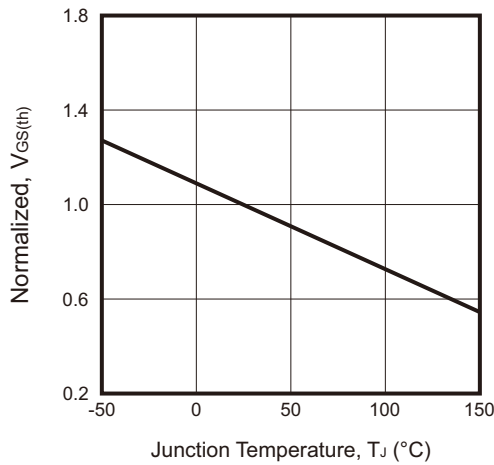


Fig.4 - Normalized  $R_{DS(ON)}$  vs.  $T_J$

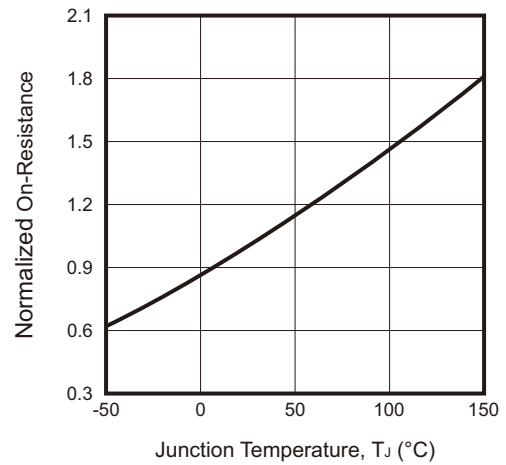


Fig.5 - Safe Operating Area

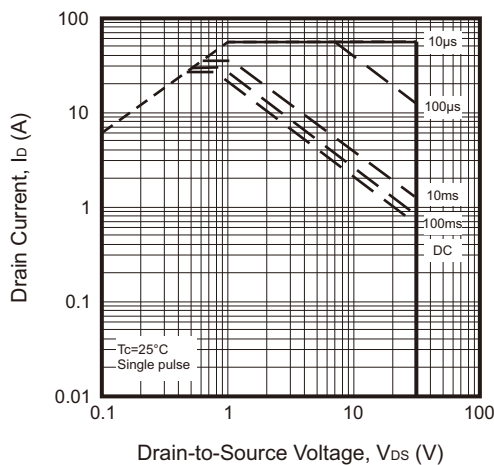
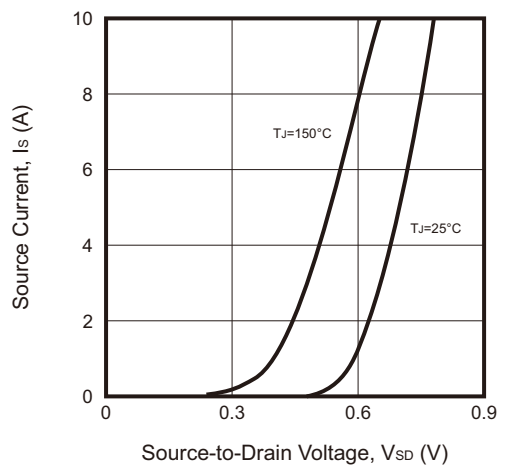


Fig.6 - Forward Characteristics of Reverse



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## Rating and Characteristic Curves (CMS25N03V8-HF)

Fig.7 - Gate Charge Characteristics

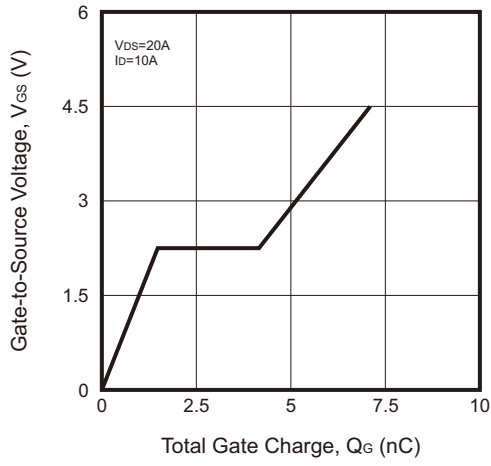
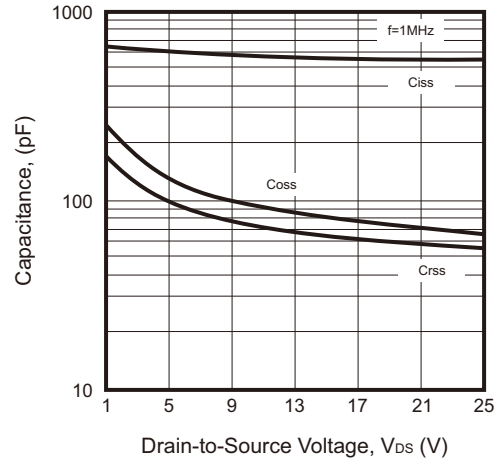
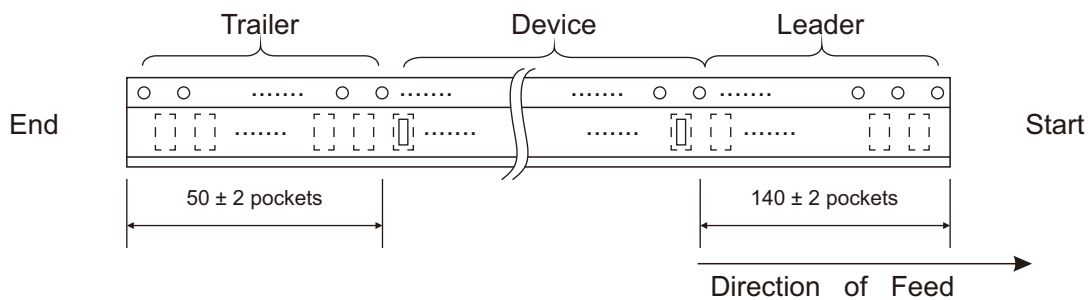
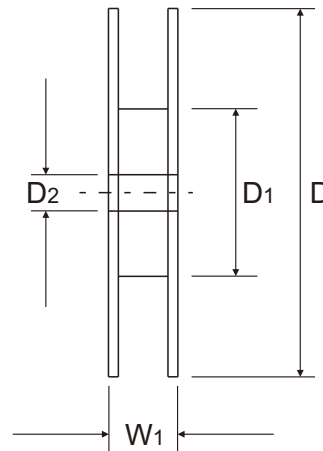
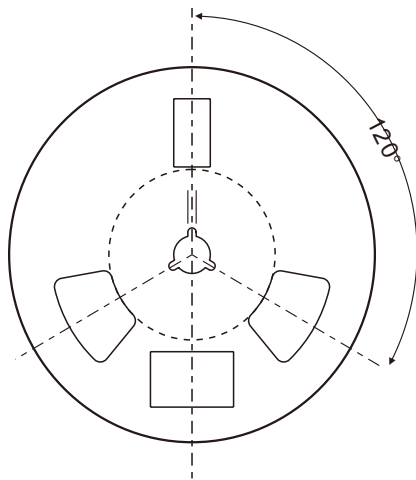
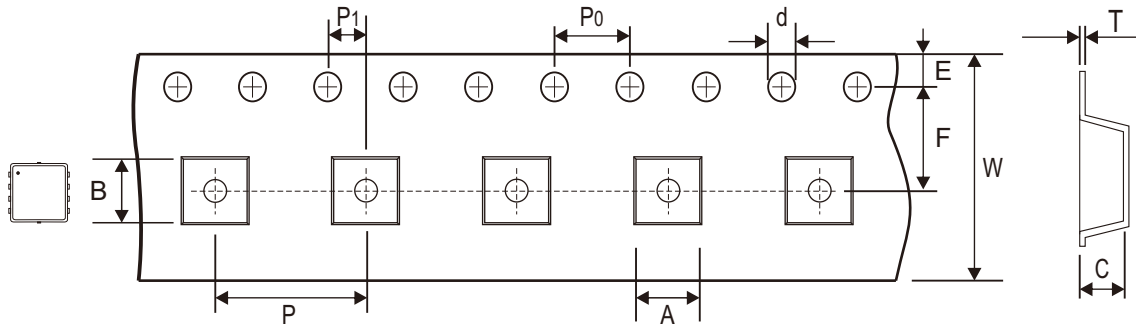


Fig.8 - Capacitance Characteristics



Reel Taping Specification



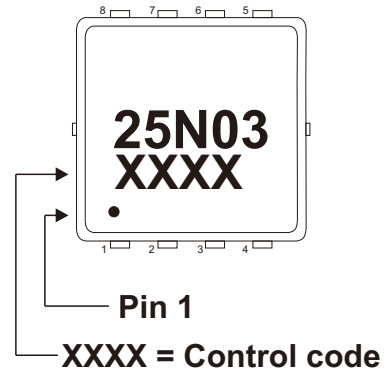
SPR-PAK	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	3.55 ± 0.10	3.55 ± 0.10	1.10 + 0.10 - 0.05	1.50 + 0.10 - 0.00	330.00 ± 1.00	178.00 + 0.00 - 2.00	13.00 min.
	(inch)	0.140 ± 0.004	0.140 ± 0.004	0.043 + 0.004 - 0.002	0.059 + 0.004 - 0.000	12.992 ± 0.039	7.008 + 0.000 - 0.079	0.512 min.

SPR-PAK	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	1.75 ± 0.10	5.50 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.30 ± 0.05	12.00 + 0.30 - 0.10	18.40 ref.
	(inch)	0.069 ± 0.004	0.217 ± 0.002	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.012 ± 0.002	0.472 + 0.012 - 0.004	0.724 ref.

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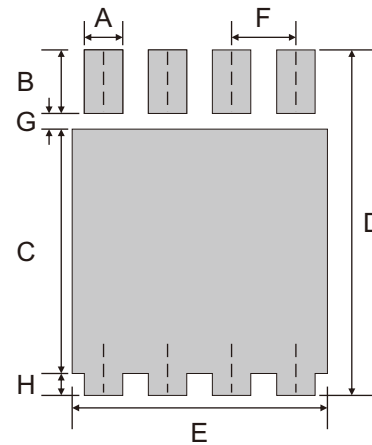
## Marking Code

Part Number	Marking Code
CMS25N03V8-HF	25N03 XXXX



## Suggested PAD Layout

SIZE	SPR-PAK (PDFN3.3x3.3)	
	(mm)	(inch)
A	0.40	0.016
B	0.60	0.024
C	2.35	0.093
D	3.55	0.140
E	2.80	0.110
F	0.65	0.026
G	0.35	0.014
H	0.25	0.010



Note: 1. The pad layout is for reference purposes only.

## Standard Packaging

Case Type	REEL PACK	
	REEL ( pcs )	Reel Size (inch)
SPR-PAK (PDFN3.3x3.3)	3000	13